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**Part Number:** [73780-1235](#)  
**Status:** **Active**  
**Overview:** [HDM®](#)  
**Description:** 2.00mm Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 15.00mm, Pin Length 2.00mm, Solder Tail

**Documents:**

[3D Model](#) [Test Summary TS-73670-990 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Product Specification PS-73780-999 \(PDF\)](#)

**General**

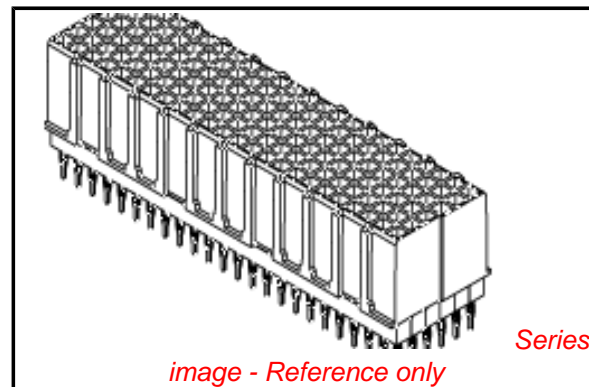
|                |                         |
|----------------|-------------------------|
| Product Family | Backplane Connectors    |
| Series         | <a href="#">73780</a>   |
| Application    | Daughtercard, Mezzanine |
| Comments       | Solder Tail             |
| Component Type | PCB Receptacle          |
| Overview       | <a href="#">HDM®</a>    |
| Product Name   | HDM®                    |
| Style          | N/A                     |
| UPC            | 822348495573            |

**Physical**

|                                |                                |
|--------------------------------|--------------------------------|
| Circuits (Loaded)              | 144                            |
| Circuits (maximum)             | 144                            |
| Color - Resin                  | Black                          |
| Durability (mating cycles max) | 250                            |
| First Mate / Last Break        | No                             |
| Guide to Mating Part           | No                             |
| Keying to Mating Part          | None                           |
| Material - Metal               | Copper-Nickel-Tin              |
| Material - Plating Mating      | Gold                           |
| Material - Plating Termination | Tin                            |
| Material - Resin               | High Temperature Thermoplastic |
| Net Weight                     | 20.030/g                       |
| Number of Columns              | 24                             |
| Number of Pairs                | Open Pin Field                 |
| Number of Rows                 | 6                              |
| Orientation                    | Vertical                       |
| PC Tail Length                 | 2.50mm                         |
| PCB Locator                    | No                             |
| PCB Retention                  | None                           |
| PCB Thickness - Recommended    | 1.60mm                         |
| Packaging Type                 | Tube                           |
| Pitch - Mating Interface       | 2.00mm                         |
| Pitch - Termination Interface  | 2.00mm                         |
| Plating min - Mating           | 0.762µm                        |
| Plating min - Termination      | 2.540µm                        |
| Polarized to PCB               | No                             |
| Stackable                      | Yes                            |
| Surface Mount Compatible (SMC) | Yes                            |
| Temperature Range - Operating  | -55°C to +105°C                |
| Termination Interface: Style   | Through Hole                   |

**Electrical**

|                               |         |
|-------------------------------|---------|
| Current - Maximum per Contact | 15A, 1A |
|-------------------------------|---------|



**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC  
Contains SVHC: No**  
**Low-Halogen Status  
Low-Halogen**

**China RoHS**



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For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73780Series](#)

**Mates With**

HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

|                         |          |
|-------------------------|----------|
| Data Rate               | 1.0 Gbps |
| Real Signals (per 25mm) | 75       |
| Shielded                | No       |
| Voltage - Maximum       | 250V AC  |

#### **Solder Process Data**

|  |                        |
|--|------------------------|
| Duration at Max. Process Temperature (seconds) | 5                      |
| Lead-free Process Capability                   | Wave Capable (TH only) |
| Max. Cycles at Max. Process Temperature        | 1                      |
| Process Temperature max. C                     | 260                    |

#### **Material Info**

#### **Reference - Drawing Numbers**

|                       |              |
|-----------------------|--------------|
| Product Specification | PS-73780-999 |
| Sales Drawing         | SD-73780-004 |
| Test Summary          | TS-73670-990 |

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